

## **ABSTRACT**

**[0023]** A method for producing a molded flip chip package is described.

According to one embodiment, an incomplete flip chip package comprising a thin substrate and a silicon chip is placed in a mold, and a resin is injected into the mold filling the gap between the surface of the flip chip and the adjacent substrate, and the resin is cured by maintaining the mold at an elevated temperature for a predetermined amount of time.